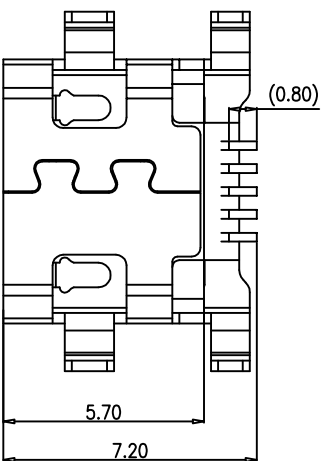
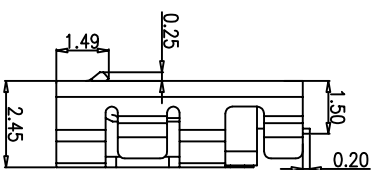
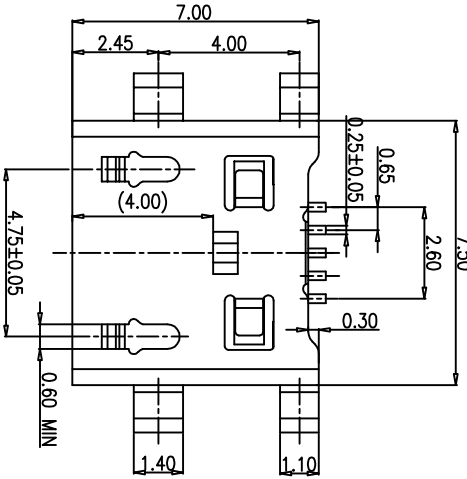
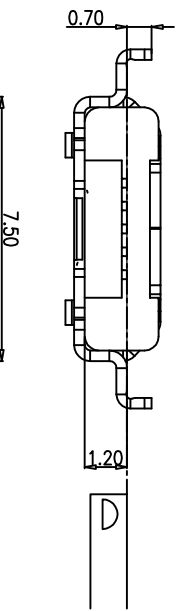
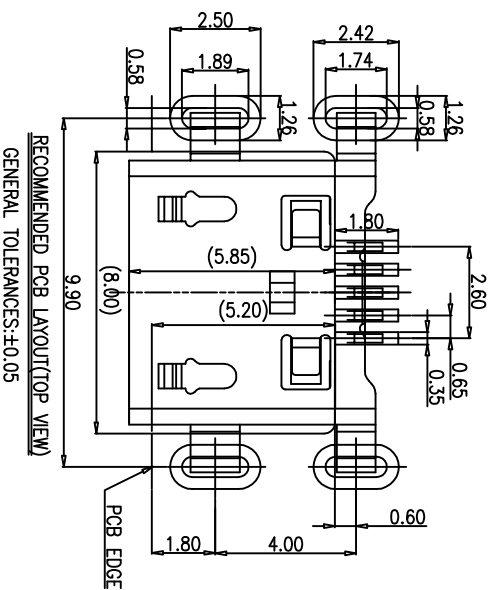


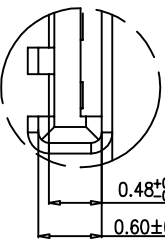
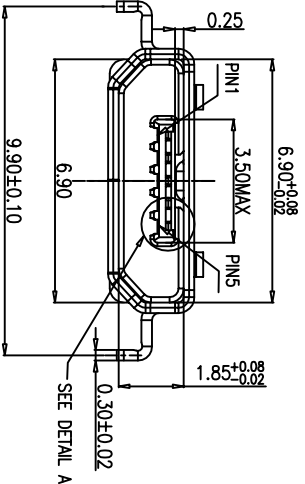
REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE



3D VIEW



RECOMMENDED PCB LAYOUT(TOP VIEW)  
GENERAL TOLERANCES:±0.05



DETAIL A  
SCALE 3:1

- NOTES:
- MATERIAL:
    - HOUSING: LCP MG-350 BPR L UL94V-0 (Supplier:JX NIPPON OIL)
    - CONTACT: C5191 R-H 0.15T(Supplier: china-zhonghuan)
    - SHELL: SUS304 1/2H 0.3T(Supplier: posco-gd)
  - FINISH:
    - CONTACT: 30"Min Au PLATED ON CONTACT AREA  
G/F PLATING ON SOLDER TAIL AREA  
50~80" NICKEL UNDERPLATING OVERALL
    - SHELL: 80~120" MATTER TIN PLATING ALL  
30~50" NICKEL UNDERPLATING OVERALL
  - SPECIFICATION:
    - CURRENT RATING: 0.5A(2.34CONTACT)/1.8A(1.5CONTACT) MAX.
    - VOLTAGE: 30VAC
    - TEMPERATURE RANGE: -30 °C ~ 85 °C
    - CONTACT RESISTANCE: 30 MILLIONHM MAX
    - DIELECTRIC WITHSTANDING VOLTAGE: 250 VAC r.m.s
    - INSULATION RESISTANCE: 100 MEGOHMS MIN.

主要技术参数	
额定电负荷	DC 30V(D. 5A)
接触电阻	≤0.03Ω
绝缘电阻	≥100KΩ
耐压	AC500V(50Hz)/min
插拔力	3~20N
使用温度范围	-30~70℃
使用寿命	5000次

PART NO:		MATERIAL: SEE NOTE	
MODEL NO:	XX	FINSH:	SEE NOTE
UNIT:	MM	COLOR:	SEE NOTE
SIZE:	A4	DR:	
TOLERANCE UNSPECIFIED		CHK:	
.X	±0.2	APP:	
.XX	±0.15		
.xxx	±0.1		
Ang.	±1'		

TITLE:		DWG NO:		SCALE:		DATE:		REV:	
深圳市迈瑞康电子有限公司		MRK-MU09-700-0032		1:1				A	
MICRO USB SP CONN 4DIP TYPE									

